

IN THE CLAIMS

Please amend claim 1 and cancel claims 13-24 as follows:

1.(Currently amended) An area array package, comprising:

a substrate having a die attach area for mounting a die to the substrate, the die having a plurality of bond pads;

at least one bond island located on the substrate; [and]

at least one bond wire for connecting at least one bond pad to at least one bond island;

a plurality of solder balls connected to the bond islands, the plurality of solder balls being located inwardly from an edge of the substrate; and

at least one redundant solder ball to allow a path for the inner solder balls connected to bond islands to be electrically plated.

2. (Original) The area array package of claim 1, further comprising an encapsulant for environmentally protecting the package.

3. (Original) The area array package of claim 1, further comprising a trace for coupling at least one bond island to a package lead located on one side of the substrate.

4. (Original) The area array package of claim 1, further comprising a via for coupling at least one bond island to the package lead.

5. (Original) The area array package of claim 3, wherein the die attach area is located on a side of the substrate that is opposite the side of the package lead.

6. (Original) The area array package of claim 3, wherein the package lead is a solder ball included in a ball grid array (BGA).

7. (Original) The area array package of claim 3, wherein the package lead is a land included in a land grid array (LGA).

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... package of claim 1, further comprising at least one bond finger for coupling a bond wire between at least one bond finger and at least one bond pad.

9. (Original) The area array package of claim 8, further comprising a trace for coupling the bond finger to a package lead.

10. (Original) The area array package of claim 8, further comprising a via for coupling the bond finger to a package lead.

11. (Original) The area array package of claim 1, wherein the substrate comprises a plurality of die attach areas for mounting a plurality of die.

12. (Original) The area array package of claim 1, wherein the substrate is a laminate substrate.

13. (Canceled)

14. (Canceled)

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24. (Canceled)

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